10-PY12PMA025SH01-P589A81Y
datasheet

***flow*PIM 1** **1200 V / 25 A**

Topology features

- Kelvin Emitter for improved switching performance
- Open Emitter configuration
- Temperature sensor
- Converter+Brake+Inverter
- Tandem diode

Component features

- Easy paralleling
- High speed switching
- Low switching losses

Housing features

- Base isolation: Al_2O_3
- Convex shaped substrate for superior thermal contact
- Thermo-mechanical push-and-pull force relief
- Press-fit pin
- Reliable cold welding connection

Extra features

- Tandem FWD concept

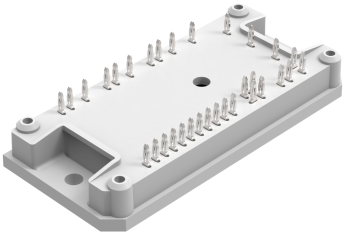
Target applications

- Embedded Drives
- Industrial Drives

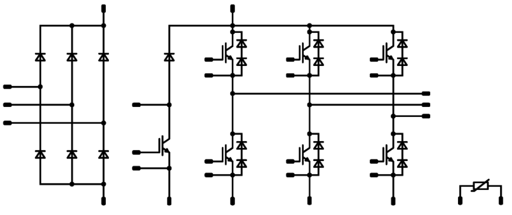
Types

- 10-PY12PMA025SH01-P589A81Y

flow 1 12 mm housing



Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	31	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		75	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	94	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1300	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	31	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		60	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	91	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	22	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		45	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	65	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	10	µs
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Brake Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	19	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	46	W
Maximum junction temperature	T_{jmax}			175	°C
Rectifier Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	46	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	270	A
Surge current capability	I^2t			370	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	56	W
Maximum junction temperature	T_{jmax}			150	°C

Module Properties

Parameter	Symbol	Conditions		Value	Unit
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				>12,7	mm
Clearance				7,96	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,00085	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		25	25 125 150	1,78	1,98 2,38 2,48	2,42(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			2,4	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_{g}							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		1430		pF
Output capacitance	C_{oes}							115		pF
Reverse transfer capacitance	C_{res}							75		pF
Gate charge	Q_{g}	V_{CC} = 960 V	15		25	25		115		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,01		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 8 Ω R_{goff} = 8 Ω	±15	600	25	25 125 150		43,2 43,68 43,84		ns
Rise time	t_{r}					25 125 150		18,72 20 20,64		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		138,24 192,16 202,88		ns
Fall time	t_{f}					25 125 150		46,38 96,22 108,98		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,784 µC Q_{rFWD}=1,59 µC Q_{rFWD}=1,86 µC				25 125 150		0,87 1,3 1,47		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,04 1,69 1,92		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Diode										
Static										
Forward voltage	V_F				30	25 125 150		3,19 3,01 2,93	3,84(1)	V
Reverse leakage current	I_R	V_r = 1300 V				25			1,6	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,04		K/W
Dynamic										
Peak recovery current	I_{RM}	d*i*/d*t*=1369 A/µs d*i*/d*t*=1305 A/µs d*i*/d*t*=1250 A/µs	±15	600	25	25 125 150		13,29 18,55 19,84		A
Reverse recovery time	t_{rr}					25 125 150		78,2 130,09 149,56		ns
Recovered charge	Q_r					25 125 150		0,784 1,59 1,86		µC
Reverse recovered energy	E_{rec}					25 125 150		0,277 0,561 0,656		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		479,77 174,01 151,66		A/µs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,0005	25	5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150	1,58	1,87 2,14 2,21	2,07(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			2	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		890		pF
Reverse transfer capacitance	C_{res}	f = 1 Mhz	0	25		25		30		pF
Gate charge	Q_g		20		0	25		120		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,45		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		86,8 86,6 88		ns
Rise time	t_r	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		24,2 27,8 28,6		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		193,6 256 257,8		ns
Fall time	t_f	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		76,6 102,03 110,95		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=1,38 µC Q_{rFWD}=2,27 µC Q_{rFWD}=2,53 µC	±15	600	15	25 125 150		0,95 1,29 1,38		mWs
Turn-off energy (per pulse)	E_{off}		±15	600	15	25 125 150		0,824 1,17 1,27		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Diode										
Static										
Forward voltage	V_F				10	25 125 150	1,35	1,79 1,77 1,73	2,05[1]	V
Reverse leakage current	I_R	V_r = 1200 V				25			2,7	μA
Thermal										
Thermal resistance junction to sink [2]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,07		K/W
Dynamic										
Peak recovery current	I_{RM}	d*i*/d*t*=611 A/μs d*i*/d*t*=482 A/μs d*i*/d*t*=484 A/μs	±15	600	15	25 125 150		10,02 11,64 12,03		A
Reverse recovery time	t_{rr}					25 125 150		323,77 488,88 537,51		ns
Recovered charge	Q_r					25 125 150		1,38 2,27 2,53		μC
Reverse recovered energy	E_{rec}					25 125 150		0,581 0,965 1,08		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		45,97 45,75 44,44		A/μs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Rectifier Diode										
Static										
Forward voltage	V_F				13	25 125		0,988 0,899	1,21[1] 1,1[1]	V
Reverse leakage current	I_R	V_r = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink [2]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,25		K/W
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{25}	$\Delta_{R/R}$	R_{25} = 22 kΩ				25	-5		5	%
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1486 Ω				100	-12		14	%
Power dissipation	P							200		mW
Power dissipation constant	d					25		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3 %						3950		K
B-value	$B_{(25/100)}$	Tol. ±3 %						3998		K
Vincotech Thermistor Reference									B	

(1) Value at chip level

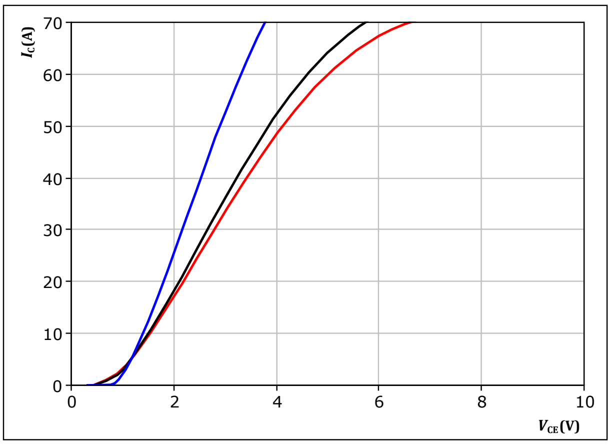
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$



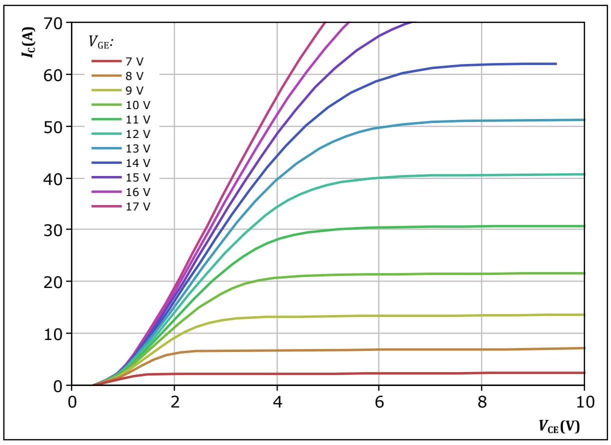
t_p =	250	µs
V_{GE} =	15	V

T_j: 25 °C, 125 °C, 150 °C

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$



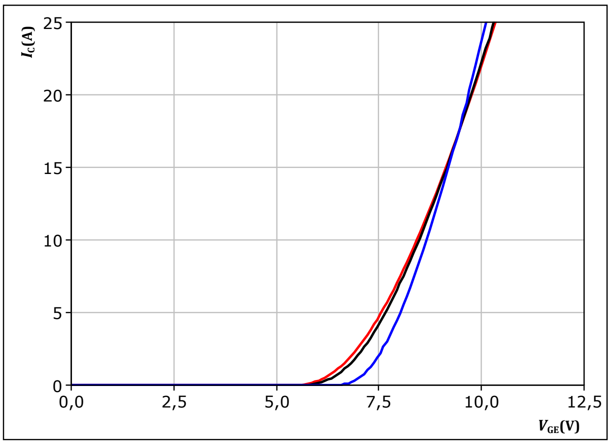
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



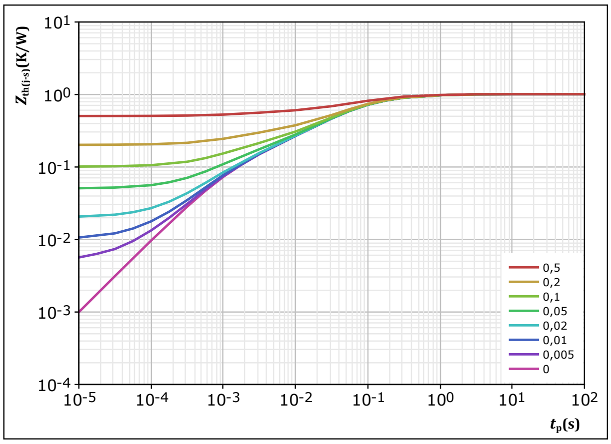
t_p =	250	µs
V_{CE} =	10	V

T_j: 25 °C, 125 °C, 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,009 K/W

IGBT thermal model values

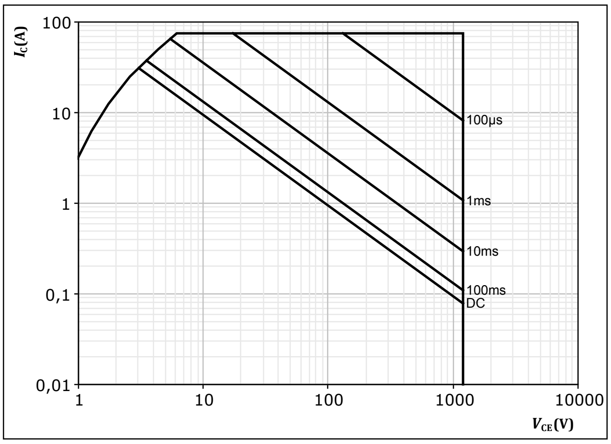
R (K/W)	τ (s)
8,44E-02	1,03E+00
2,46E-01	1,79E-01
4,48E-01	5,38E-02
1,38E-01	1,04E-02
5,48E-02	1,66E-03
3,85E-02	8,73E-04

Inverter Switch Characteristics

figure 5.	IGBT

Safe operating area

I_C = f(V_{CE})



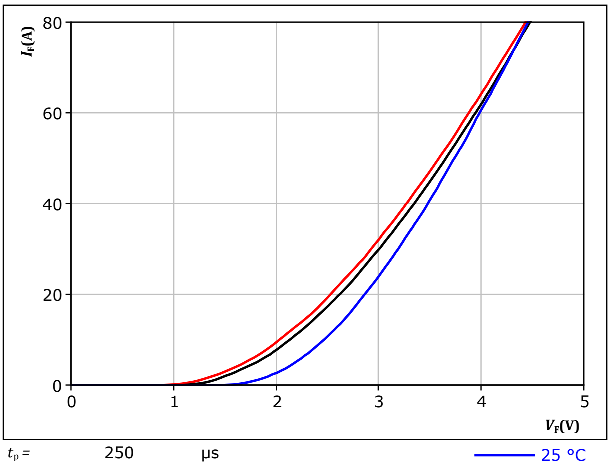
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

I_F = f(V_F)



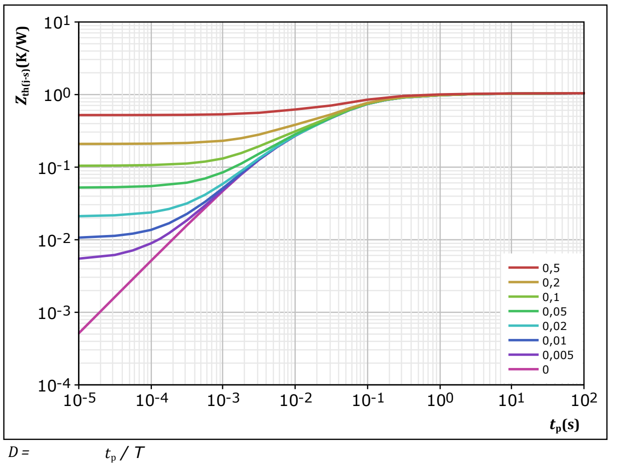
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,043 K/W

FWD thermal model values

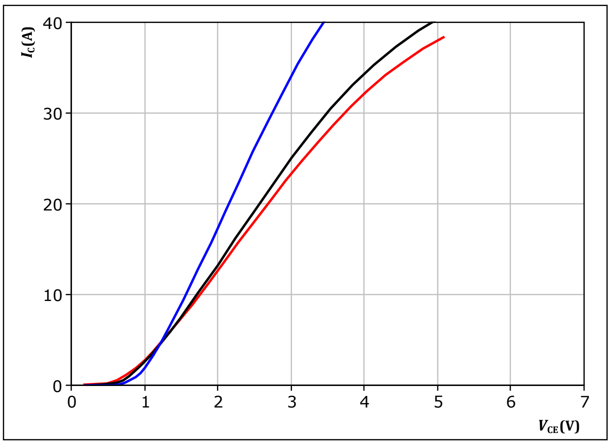
R (K/W)	τ (s)
1,84E-02	3,09E+01
9,18E-02	1,45E+00
2,98E-01	1,55E-01
4,70E-01	4,05E-02
1,65E-01	4,35E-03

Brake Switch Characteristics

figure 8. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



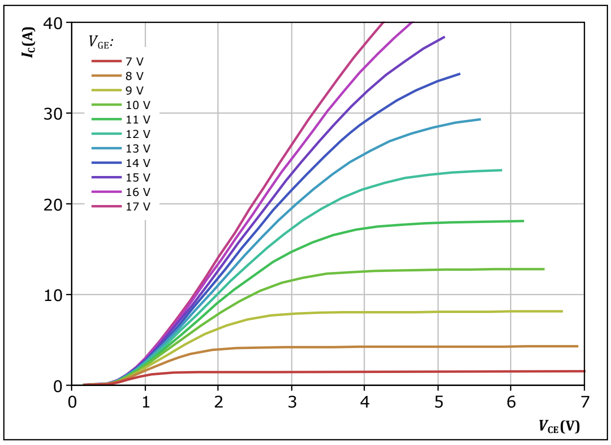
t_p =	250	µs
V_{GE} =	15	V

T_j: 25 °C / 125 °C / 150 °C

figure 9. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



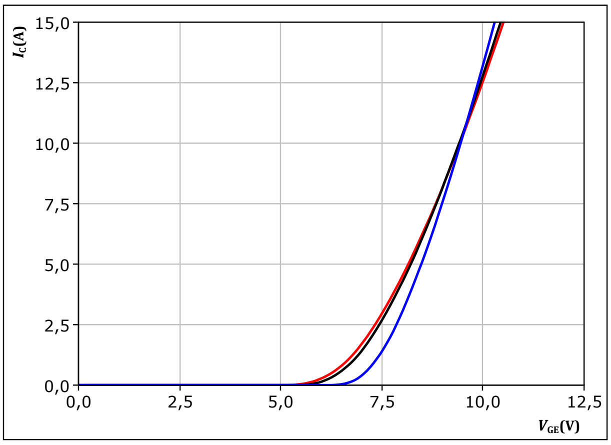
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 10. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})



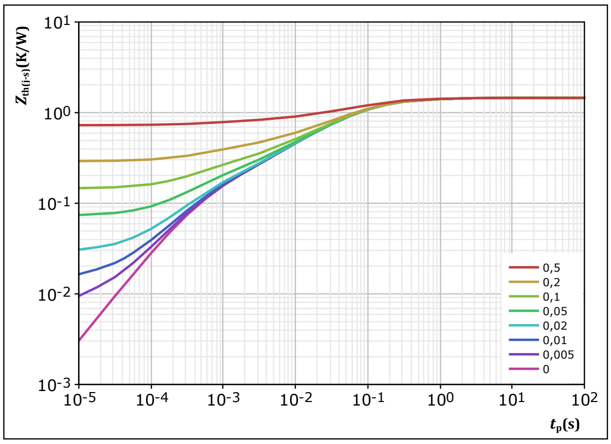
t_p =	250	µs
V_{CE} =	10	V

T_j: 25 °C / 125 °C / 150 °C

figure 11. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D =	t_p / T	
$R_{th(j-s)}$ =	1,453	K/W

IGBT thermal model values

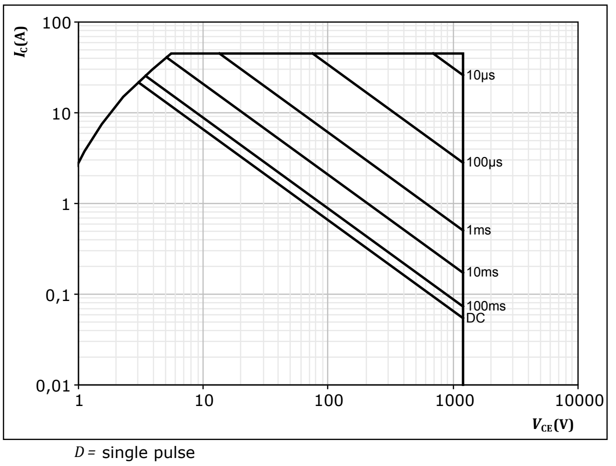
R (K/W)	τ (s)
1,02E-01	1,17E+00
3,31E-01	1,69E-01
5,63E-01	5,65E-02
2,92E-01	1,03E-02
8,13E-02	1,50E-03
8,53E-02	4,00E-04

Brake Switch Characteristics

figure 12.	IGBT

Safe operating area

I_C = f(V_{CE})



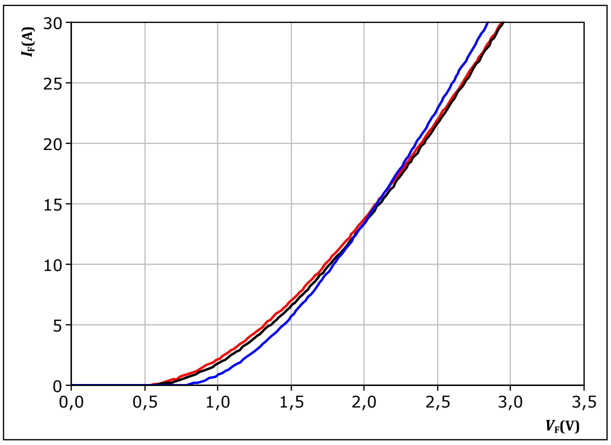
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 13. **FWD**

Typical forward characteristics

I_F = f(V_F)



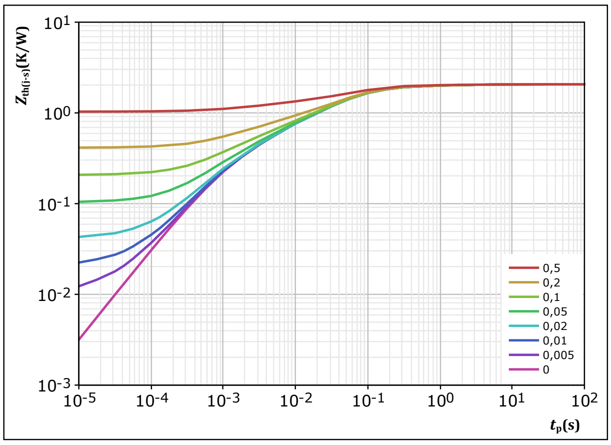
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 14. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 2,066 K/W

FWD thermal model values

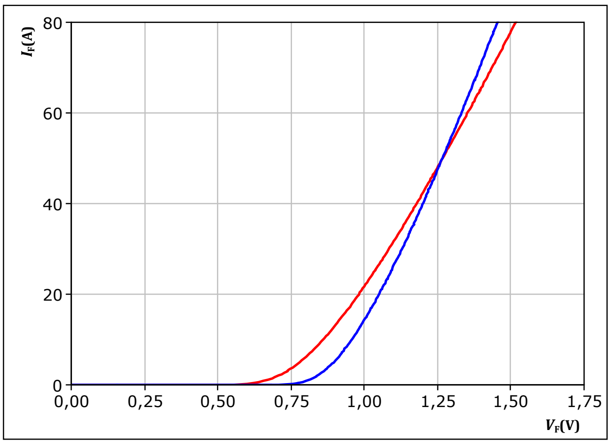
R (K/W)	τ (s)
5,09E-02	4,26E+00
1,55E-01	5,03E-01
7,75E-01	7,89E-02
5,33E-01	2,68E-02
3,54E-01	5,03E-03
1,97E-01	9,09E-04

Rectifier Diode Characteristics

figure 15. Rectifier

Typical forward characteristics

I_F = f(V_F)



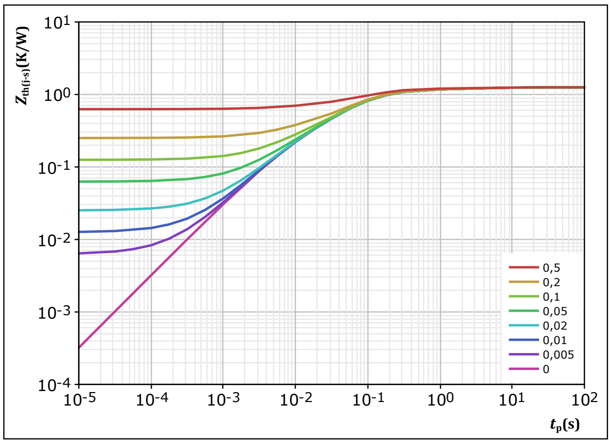
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 16. Rectifier

Transient thermal impedance as a function of pulse width

$Z_{th(j\text{-}s)}$ = f(t_p)



D = t_p / T

$R_{th(j\text{-}s)}$ = 1,254 K/W

Rectifier thermal model values

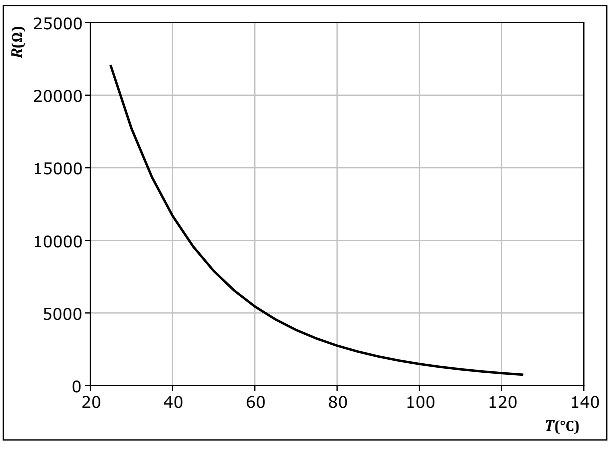
R (K/W)	τ (s)
8,00E-02	5,22E+00
1,56E-01	4,18E-01
6,95E-01	8,82E-02
2,23E-01	3,07E-02
9,97E-02	5,99E-03

Thermistor Characteristics

figure 17.	Thermistor

Typical NTC characteristic as function of temperature

R_T = f(T)

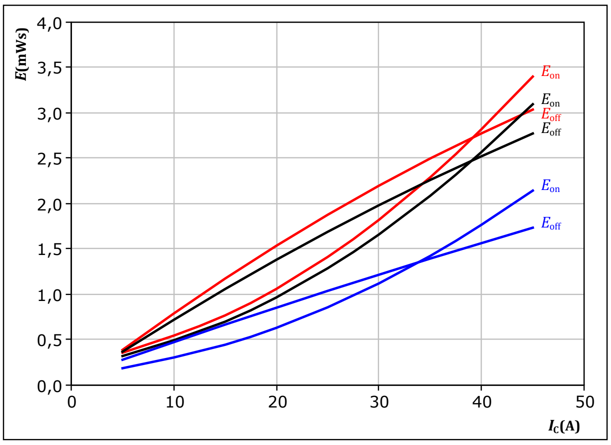


Inverter Switching Characteristics

figure 18. **IGBT**

Typical switching energy losses as a function of collector current

E = f(I_C)



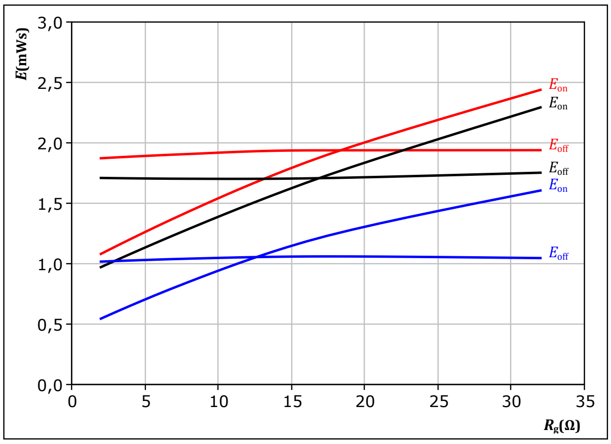
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C
R_{goff} =	8	Ω		

figure 19. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

E = f(R_g)



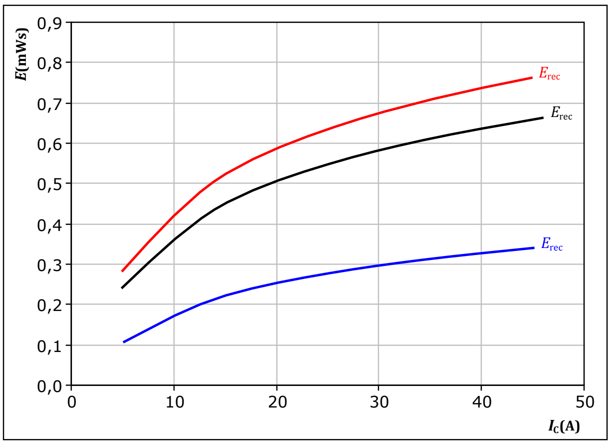
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

figure 20. **FWD**

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



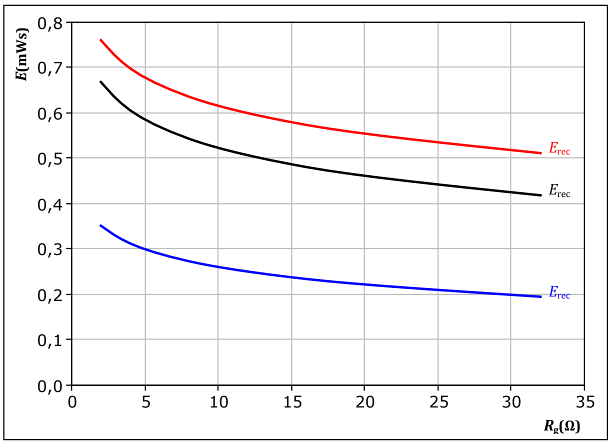
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 21. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

E_{rec} = f(R_g)



With an inductive load at

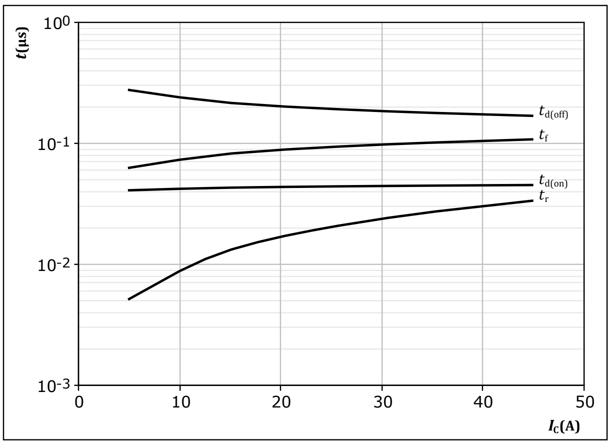
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

Inverter Switching Characteristics

figure 22. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



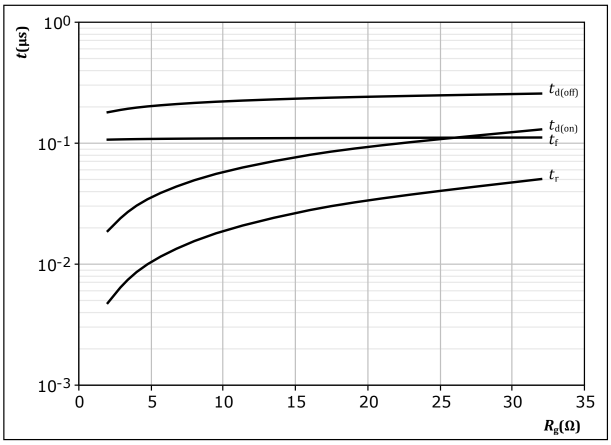
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

figure 23. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

t = f(R_g)



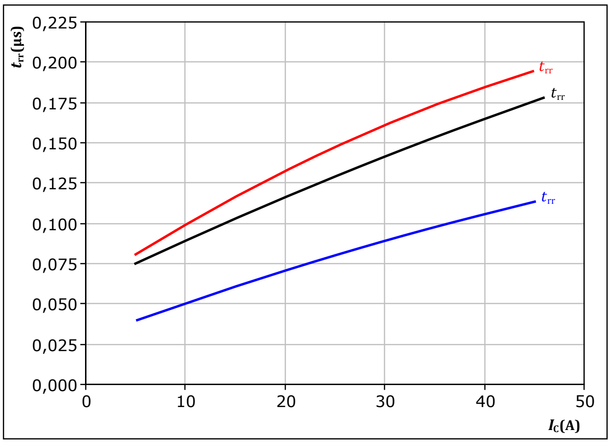
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

figure 24. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

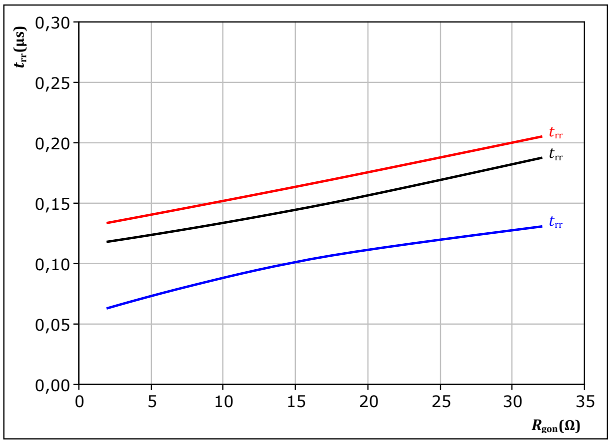
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 25. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

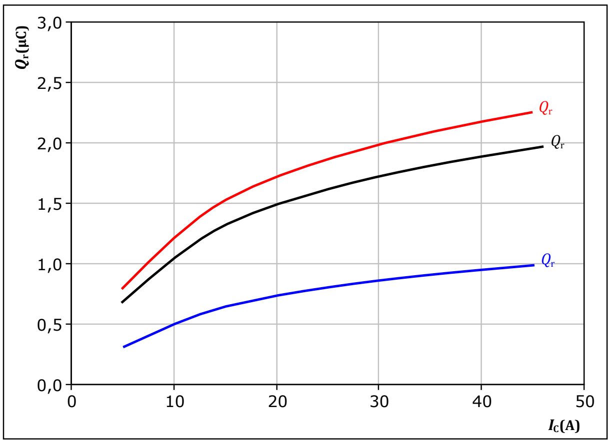
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 26. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



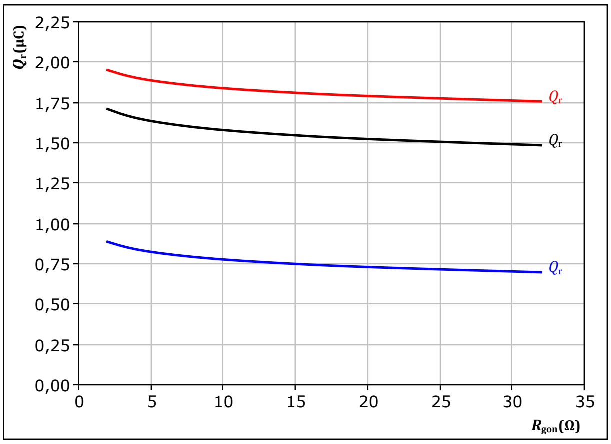
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 27. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

Q_r = f(R_{gon})



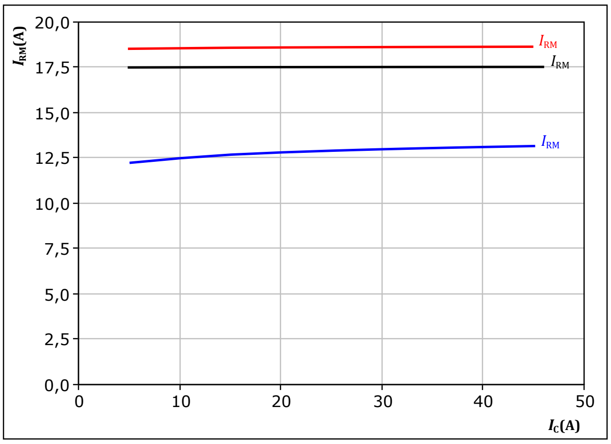
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

figure 28. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



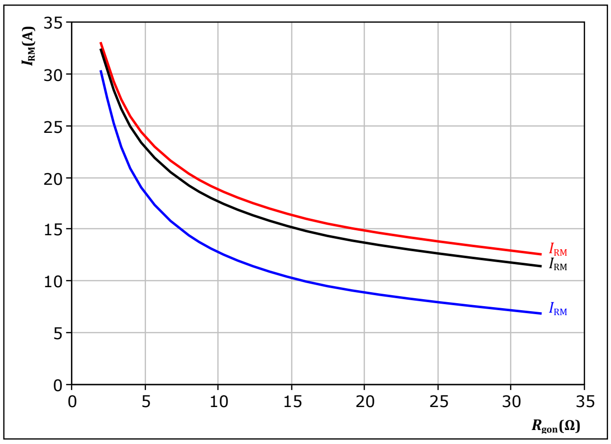
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 29. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

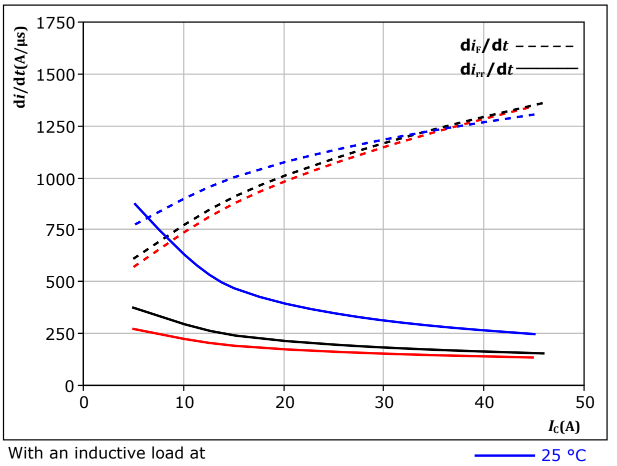
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

Inverter Switching Characteristics

figure 30. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



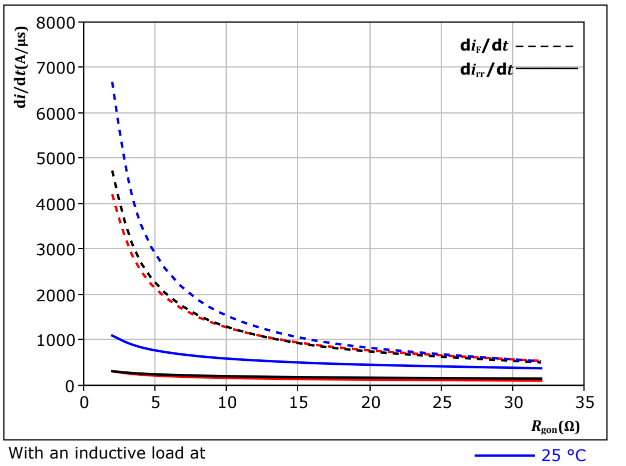
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 31. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



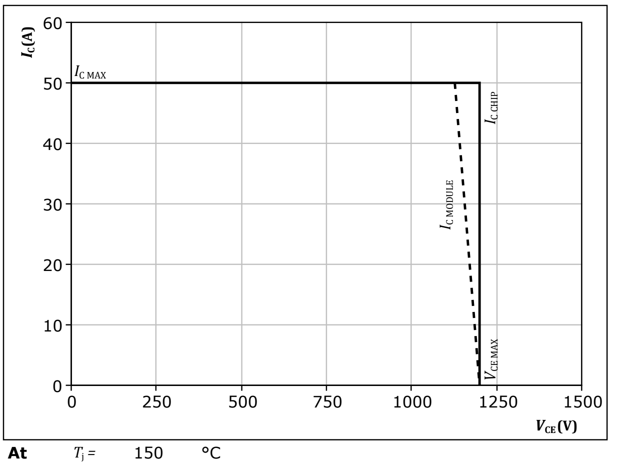
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	25	A		150 °C

figure 32. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



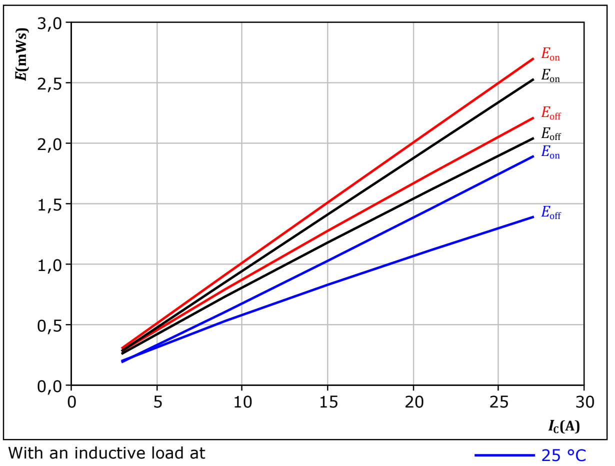
At	T_j =	150	°C
	R_{gon} =	8	Ω
	R_{goff} =	8	Ω

Brake Switching Characteristics

figure 33. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



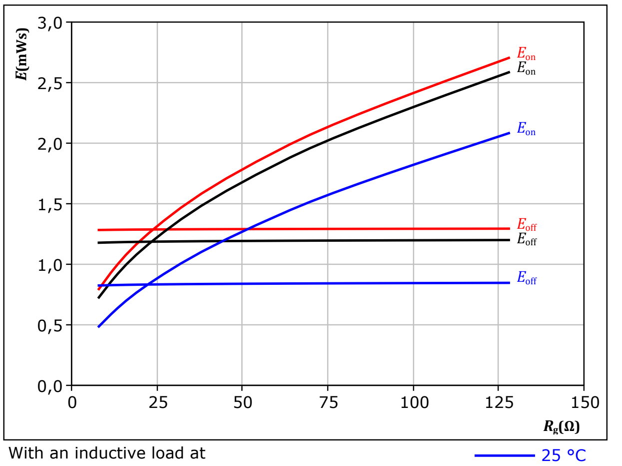
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C
R_{goff} =	32	Ω		

figure 34. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

$E = f(R_g)$



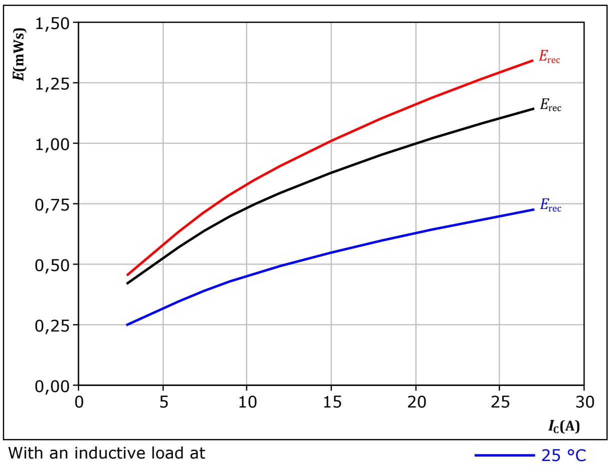
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 35. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



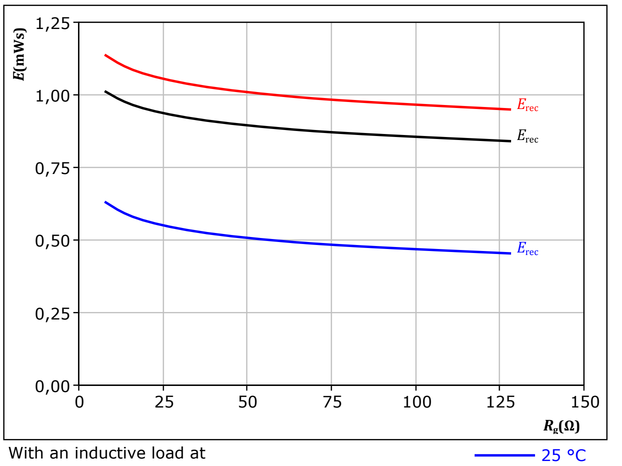
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 36. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

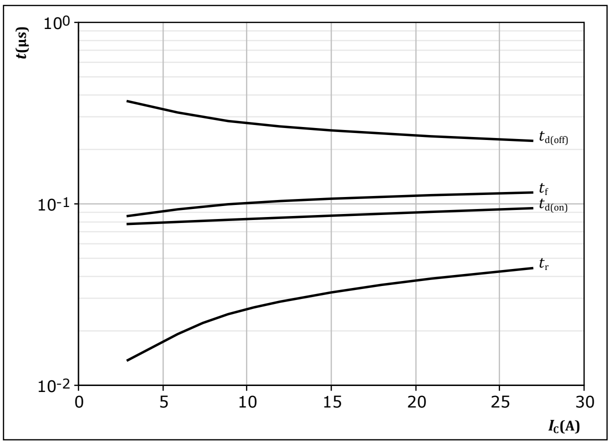
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

Brake Switching Characteristics

figure 37. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



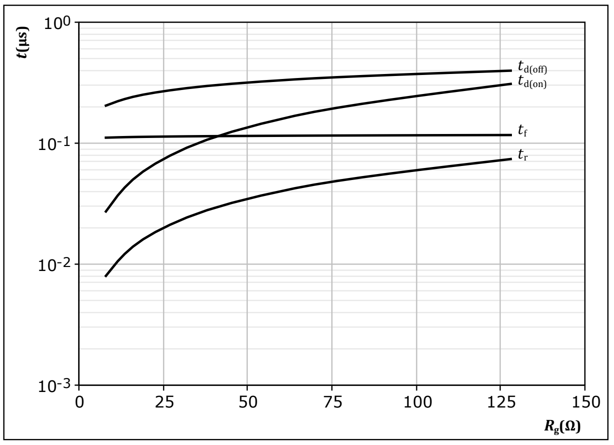
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 38. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

t = f(R_g)



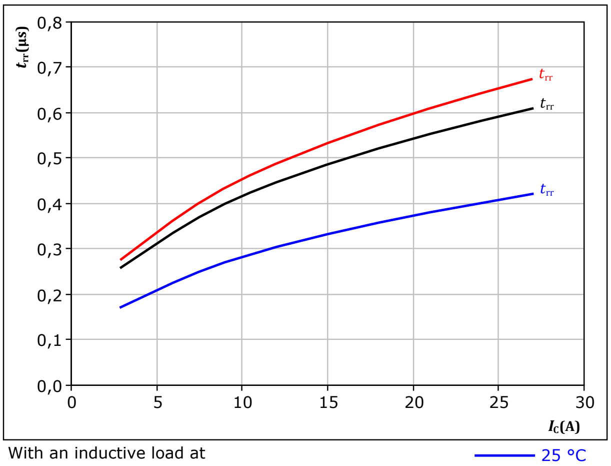
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 39. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

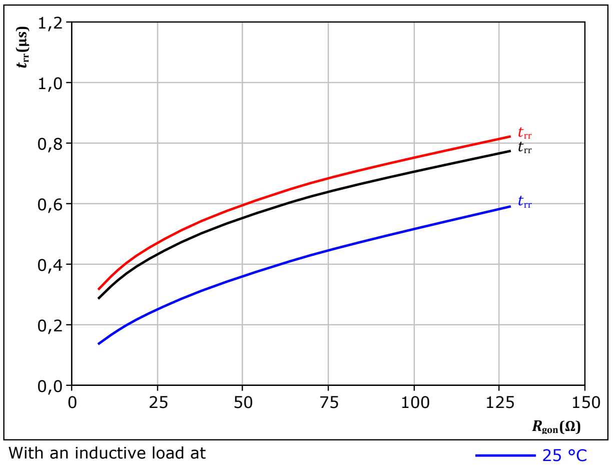
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 40. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

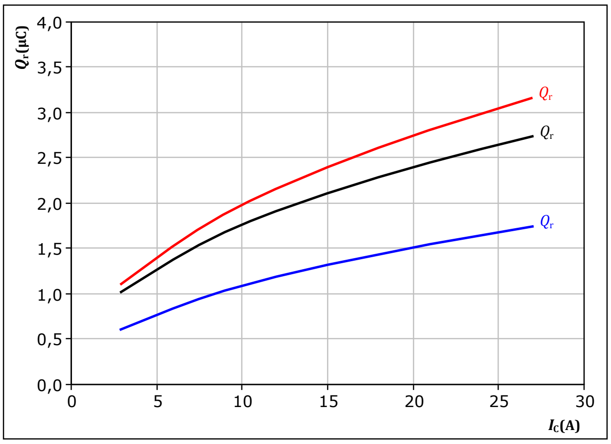
T_j: 25 °C, 125 °C, 150 °C

Brake Switching Characteristics

figure 41. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



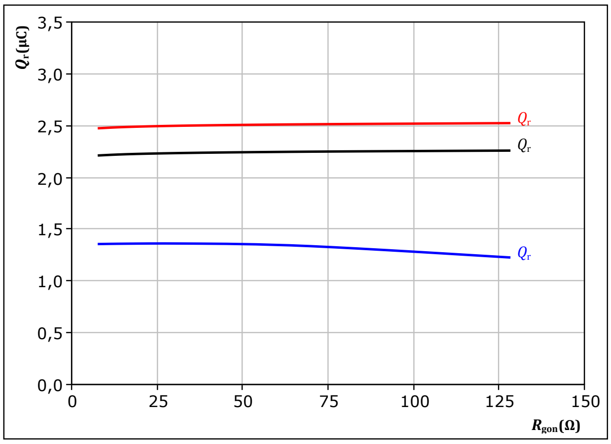
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 42. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

Q_r = f(R_{gon})



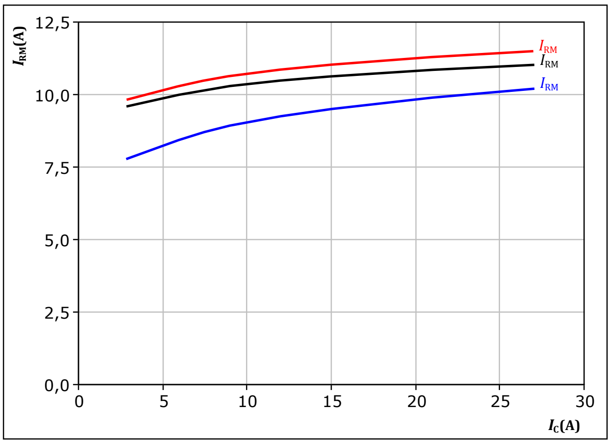
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 43. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



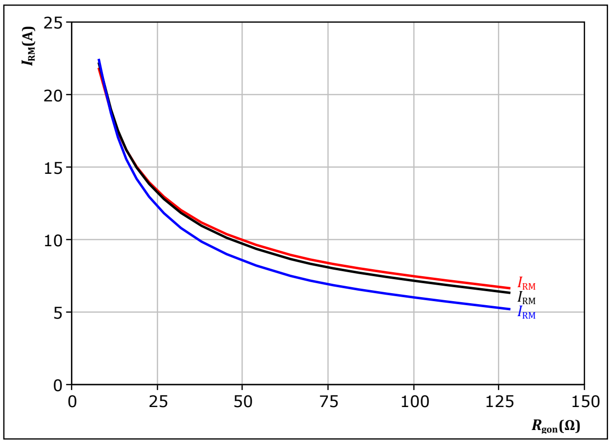
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 44. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

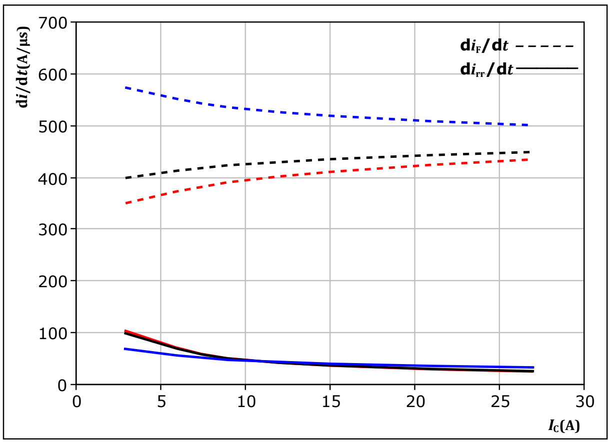
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

Brake Switching Characteristics

figure 45. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



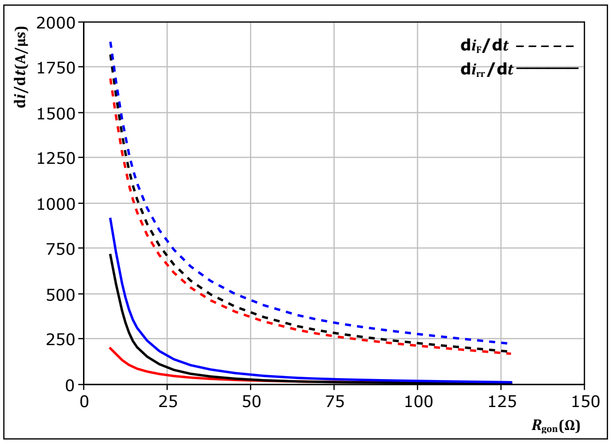
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 46. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



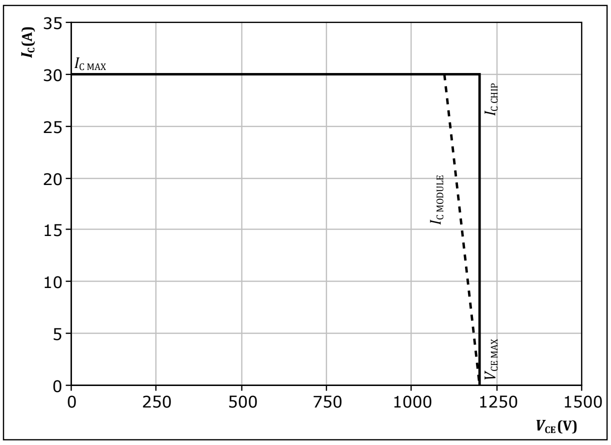
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 47. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Switching Definitions

figure 48. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

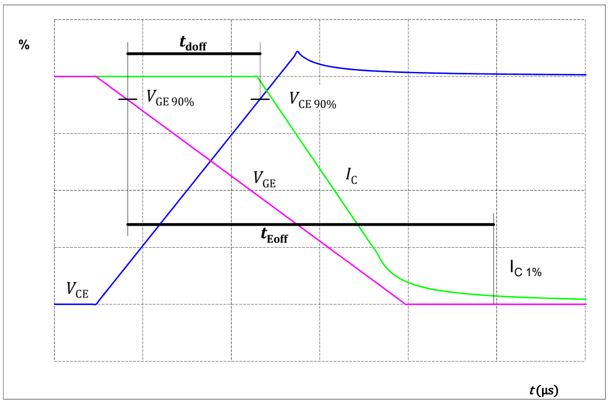


figure 49. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

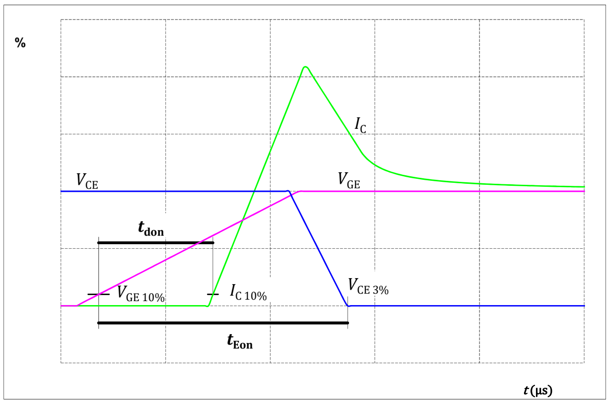


figure 50. **IGBT**

Turn-off Switching Waveforms & definition of t_f

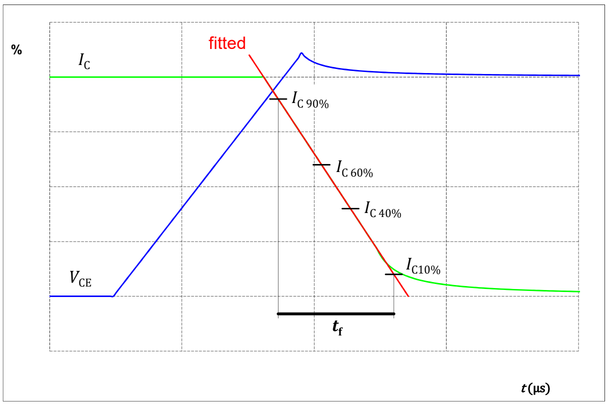
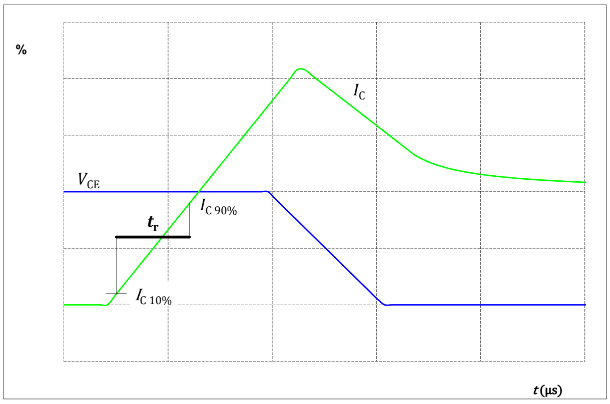


figure 51. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 52. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

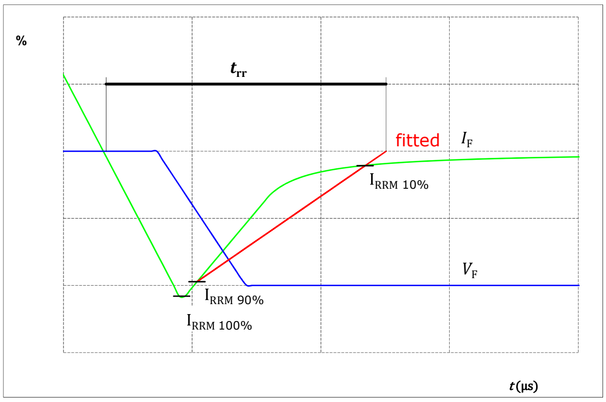
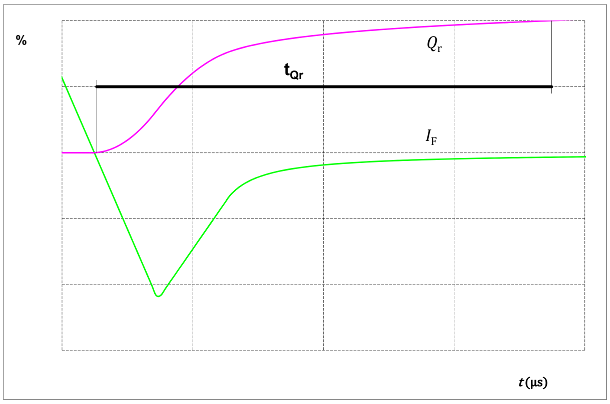


figure 53. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



Ordering Code

Version	Ordering Code
Without thermal paste	10-PY12PMA025SH01-P589A81Y
With thermal paste (5,2 W/mK, PTM6000HV)	10-PY12PMA025SH01-P589A81Y-/7/
With thermal paste (3,4 W/mK, PSX-P7)	10-PY12PMA025SH01-P589A81Y-/3/

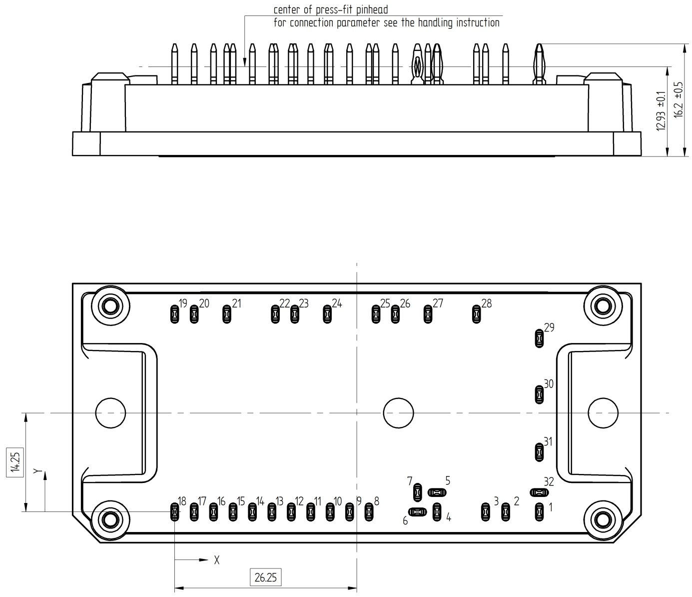
Marking

Text	**VIN**	**Date code**	**Type&Ver**	**UL**	**Lot**	**Serial**
	VIN	WWYY	TTTTTTTVV	UL	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

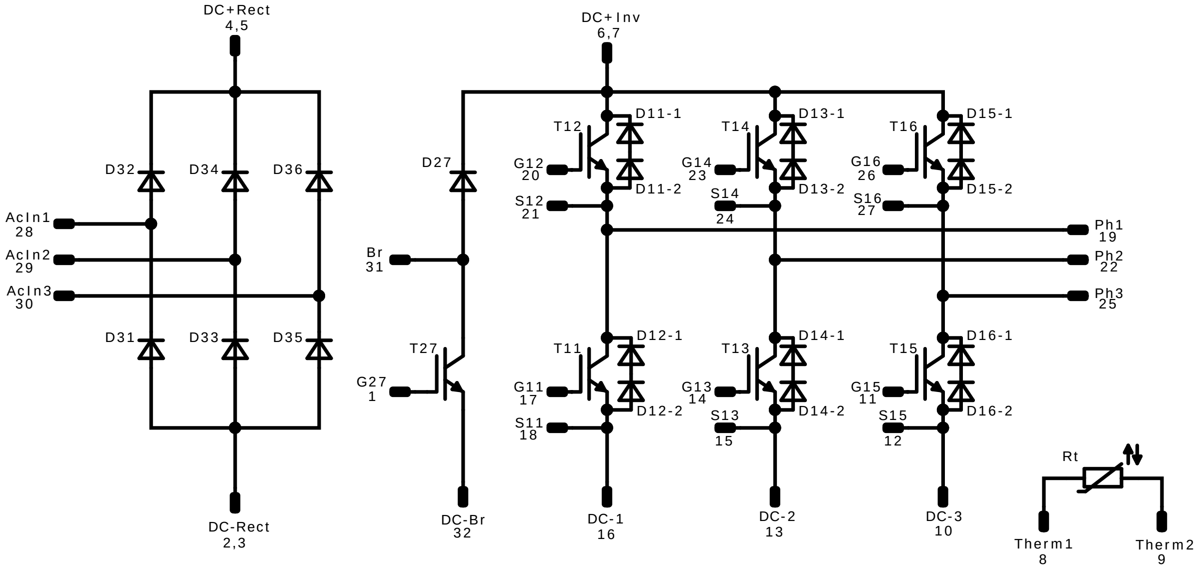
Pin	X	Y	Function
1	52,55	0	G27
2	47,7	0	DC-Rect
3	44,8	0	DC-Rect
4	37,8	0	DC+Rect
5	37,8	2,8	DC+Rect
6	35	0	DC+Inv
7	35	2,8	DC+Inv
8	28	0	Therm1
9	25,2	0	Therm2
10	22,4	0	DC-3
11	19,6	0	G15
12	16,8	0	S15
13	14	0	DC-2
14	11,2	0	G13
15	8,4	0	S13
16	5,6	0	DC-1
17	2,8	0	G11
18	0	0	S11
19	0	28,5	Ph1
20	2,8	28,5	G12
21	7,5	28,5	S12
22	14,5	28,5	Ph2
23	17,3	28,5	G14
24	22	28,5	S14
25	29	28,5	Ph3
26	31,8	28,5	G16
27	36,5	28,5	S16
28	43,5	28,5	ACIn1
29	52,55	25	ACIn2
30	52,55	16,9	ACIn3
31	52,55	8,6	Br
32	52,55	2,8	DC-Br

Pin table [mm]



Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	25 A	Inverter Switch	
D11-1, D11-2, D12-1, D12-2, D13-1, D13-2, D14-1, D14-2, D15-1, D15-2, D16-1, D16-2	FWD	1300 V	30 A	Inverter Diode	
T27	IGBT	1200 V	15 A	Brake Switch	
D27	FWD	1200 V	10 A	Brake Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	35 A	Rectifier Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 1 packages see vincotech.com website.

Package data
Package data for *flow* 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-PY12PMA025SH01-P589A81Y-D1-14	3 Mar. 2020		
10-PY12PMA025SH01-P589A81Y-D2-14	3 Aug. 2022	Vf condition of Rectifier Diode changed according to chip datasheet	